Integrated Silicon Pressure Sensor On-Chip Signal Conditioned, Temperature Compensated and Calibrated

MPVZ5010G SERIES

INTEGRATED PRESSURE SENSOR
0 to 10 kPA (0 to 1019.78 mm H_2O)
0.2 to 4.7 V OUTPUT

The MPVZ5010G series piezoresistive transducers are state-of-the-art monolithic silicon pressure sensors designed for the appliance, consumer, healthcare, industrial and automotive market. The analog output can be read directly into the A/D input of Freescale microcontrollers. This transducer combines advanced micromachining techniques, thin-film metallization, and bipolar processing to provide an accurate, high level analog output signal that is proportional to the applied pressure. The axial port has been modified to accommodate industrial grade tubing.

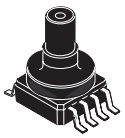
Features

- 5.0% Maximum Error over 0° to 85°C
- Temperature Compensated over -40° to +125°C
- Durable Thermoplastic (PPS) Package
- Available in Surface Mount (SMT) or Through-hole (DIP) Configurations

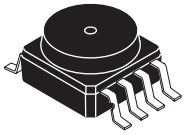
Application Examples

- Washing Machine Water Level Measurement (Reference AN1950)
- Ideally Suited for Microprocessor or Microcontroller-Based Systems
- Appliance Liquid Level and Pressure Measurement
- Respiratory Equipment

SMALL OUTLINE PACKAGE SURFACE MOUNT

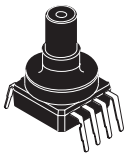


MPVZ5010GW6U
CASE 1735-01

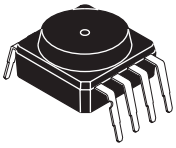


MPVZ5010G6U/T1
CASE 482-01

SMALL OUTLINE PACKAGE THROUGH-HOLE



MPVZ5010GW7U
CASE 1560-02



MPVZ5010G7U
CASE 482B-03

ORDERING INFORMATION				
Device Type	**Case No.**	**MPVZ Series Order No.**	**Packing Options**	**Device Marking**
Surface Mount	1735-01	MPVZ5010GW6U	Rails	MZ5010GW
Through-Hole	1560-02	MPVZ5010GW7U	Rails	MZ5010GW
Surface Mount	482-01	MPVZ5010G6U	Rails	MZ5010G
Surface Mount	482-01	MPVZ5010G6T1	Tape & Reel	MZ5010G
Through-Hole	482B-03	MPVZ5010G7U	Rails	MZ5010G

PIN NUMBERS[1]			
1	N/C	5	N/C
2	V_S	6	N/C
3	GND	7	N/C
4	V_{OUT}	8	N/C

1. Pins 1, 5, 6, 7, and 8 are internal device connections. Do not connect to external circuitry or ground. Pin 1 is noted by the notch in the lead.

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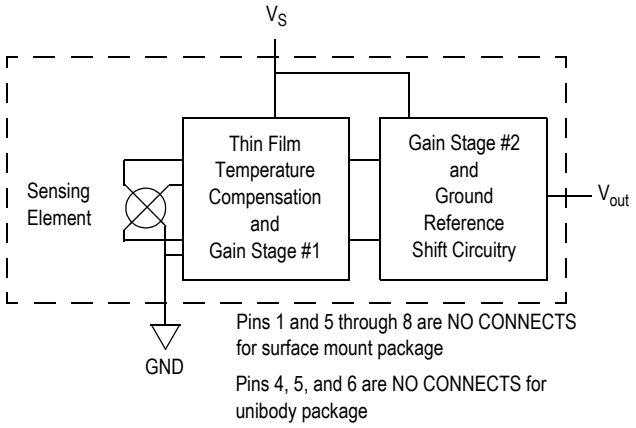


Figure 1. Fully Integrated Pressure Sensor Schematic

Table 1. Maximum Ratings[1]

Rating	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	P_{max}	40	kPa
Storage Temperature	T_{stg}	–40 to +125	°C
Operating Temperature	T_A	–40 to +125	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Table 2. Operating Characteristics (V_S = 5.0 Vdc, T_A = 25°C unless otherwise noted, P1 > P2. Decoupling circuit shown in Figure 3 required to meet specification.)

Characteristic		Symbol	Min	Typ	Max	Unit
Pressure Range[1]		P_{OP}	0	—	10 1019.78	kPa mm H_2O
Supply Voltage[2]		V_S	4.75	5.0	5.25	Vdc
Supply Current		I_o	—	5.0	10	mAdc
Minimum Pressure Offset[3] @ V_S = 5.0 Volts	(0 to 85°C)	V_{off}	0	0.2	0.425	Vdc
Full Scale Output[4] @ V_S = 5.0 Volts	(0 to 85°C)	V_{FSO}	4.475	4.7	4.925	Vdc
Full Scale Span[5] @ V_S = 5.0 Volts	(0 to 85°C)	V_{FSS}	4.275	4.5	4.725	Vdc
Accuracy[6]	(0 to 85°C)	—	—	—	±5.0	$\%V_{FSS}$
Sensitivity		V/P	—	450 4.413	—	mV/kPa mV/mm H_2O
Response Time[7]		t_R	—	1.0	—	ms
Output Source Current at Full Scale Output		I_{O+}	—	0.1	—	mAdc
Warm-Up Time[8]		—	—	20	—	ms
Offset Stability[9]		—	—	±0.5	—	$\%V_{FSS}$

1. 1.0 kPa (kiloPascal) equals 0.145 psi.
2. Device is ratiometric within this specified excitation range.
3. Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.
4. Full Scale Output (V_{FSO}) is defined as the output voltage at the maximum or full rated pressure.
5. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
6. Accuracy (error budget) consists of the following:
   - Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.
   - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
   - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25°C.
   - TcSpan: Output deviation over the temperature range of 0° to 85°C, relative to 25°C.
   - TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0° to 85°C, relative to 25°C.
   - Variation from Nominal: The variation from nominal values, for Offset or Full Scale Span, as a percent of V_{FSS}, at 25°C.
7. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
8. Warm-up Time is defined as the time required for the product to meet the specified output voltage after the Pressure has been stabilized.
9. Offset Stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

ON-CHIP TEMPERATURE COMPENSATION, CALIBRATION AND SIGNAL CONDITIONING

The performance over temperature is achieved by integrating the shear-stress strain gauge, temperature compensation, calibration and signal conditioning circuitry onto a single monolithic chip.

Figure 2 illustrates the Differential or Gauge configuration in the basic chip carrier (Case 482). A gel die coat isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm.

The MPVZ5010G series pressure sensor operating characteristics, internal reliability and qualification tests are based on use of dry air as the pressure media. Media, other than dry air, may have adverse effects on sensor performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.

Figure 3 shows the recommended decoupling circuit for interfacing the integrated sensor to the A/D input of a microprocessor or microcontroller. Proper decoupling of the power supply is recommended.

Figure 4 shows the sensor output signal relative to pressure input. Typical, minimum, and maximum output curves are shown for operation over a temperature range of 0° to 85°C using the decoupling circuit shown in Figure 3. The output will saturate outside of the specified pressure range.

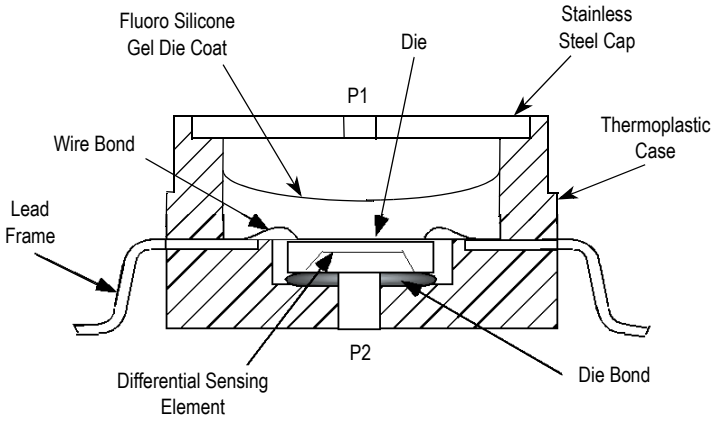


Figure 2. Cross-Sectional Diagram SOP (not to scale)

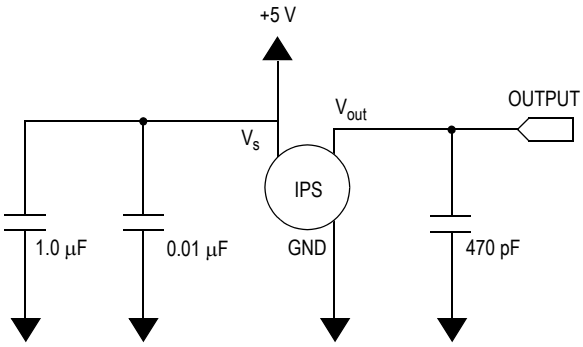


Figure 3. Recommended Power Supply Decoupling and Output Filtering
(For additional output filtering, please refer to Application Note AN1646.)

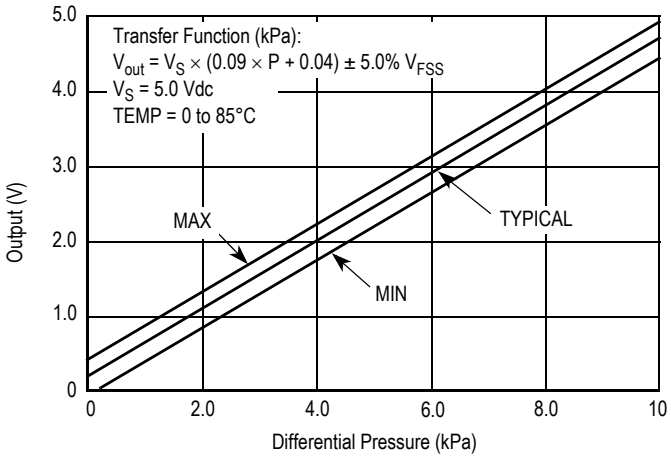


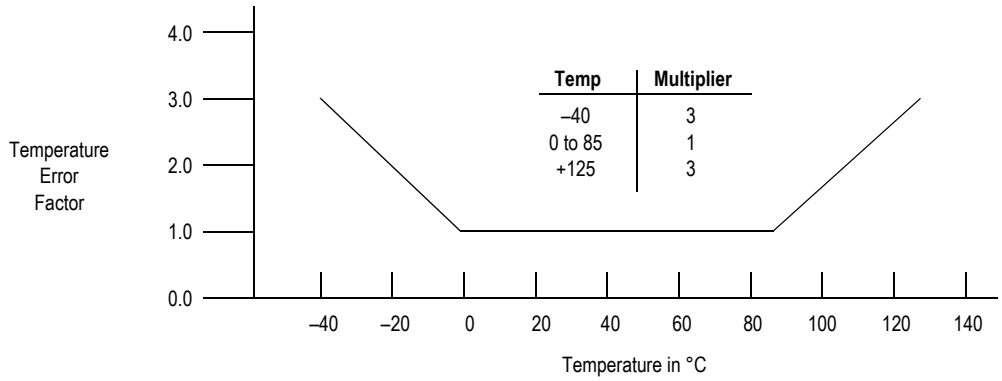
Figure 4. Output versus Pressure Differential

Transfer Function (MPVZ5010G)

Nominal Transfer Value: $V_{out} = V_S \times (0.09 \times P + 0.04)$
$\pm$ (Pressure Error x Temp. Factor x 0.09 x V_S)
$V_S = 5.0\ V \pm 0.25$ Vdc
P = kPa

Temperature Error Band

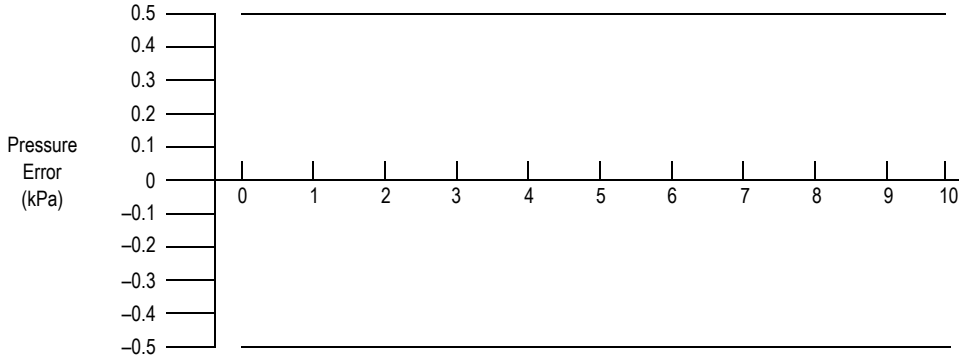
MPVZ5010G SERIES



Temp	Multiplier
–40	3
0 to 85	1
+125	3

NOTE: The Temperature Multiplier is a linear response from 0° to –40°C and from 85° to 125°C.

Pressure Error Band



Pressure	Error (Max)
0 to 10 (kPa)	±0.5 (kPa)

PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

Freescale designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing a gel die coat which protects the die from harsh media. The MPX pressure sensor is designed to operate with positive differential pressure applied, P1 > P2.

The Pressure (P1) side may be identified by using the table below:

Part Number	Case Type	Pressure (P1) Side Identifier
MPVZ5010GW6U	1735-01	Vertical Port Attached
MPVZ5010GW7U	1560-02	Vertical Port Attached
MPVZ5010G6U/T1	482-01	Stainless Steel Cap
MPVZ5010G7U	482B-03	Stainless Steel Cap

MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the surface mount packages must be the correct size to ensure proper solder connection interface between the board and the package. With the correct footprint, the packages will self align when subjected to a solder reflow process. It is always recommended to design boards with a solder mask layer to avoid bridging and shorting between solder pads.

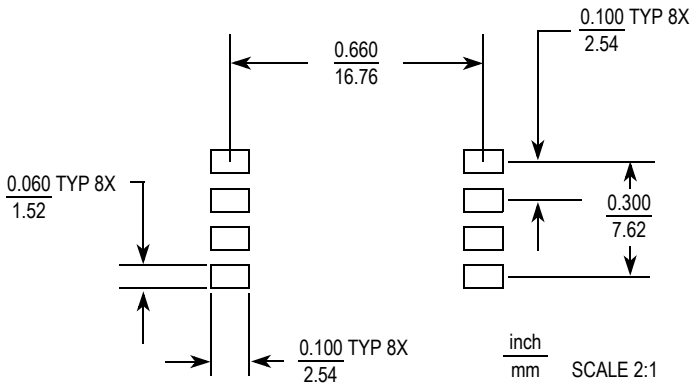
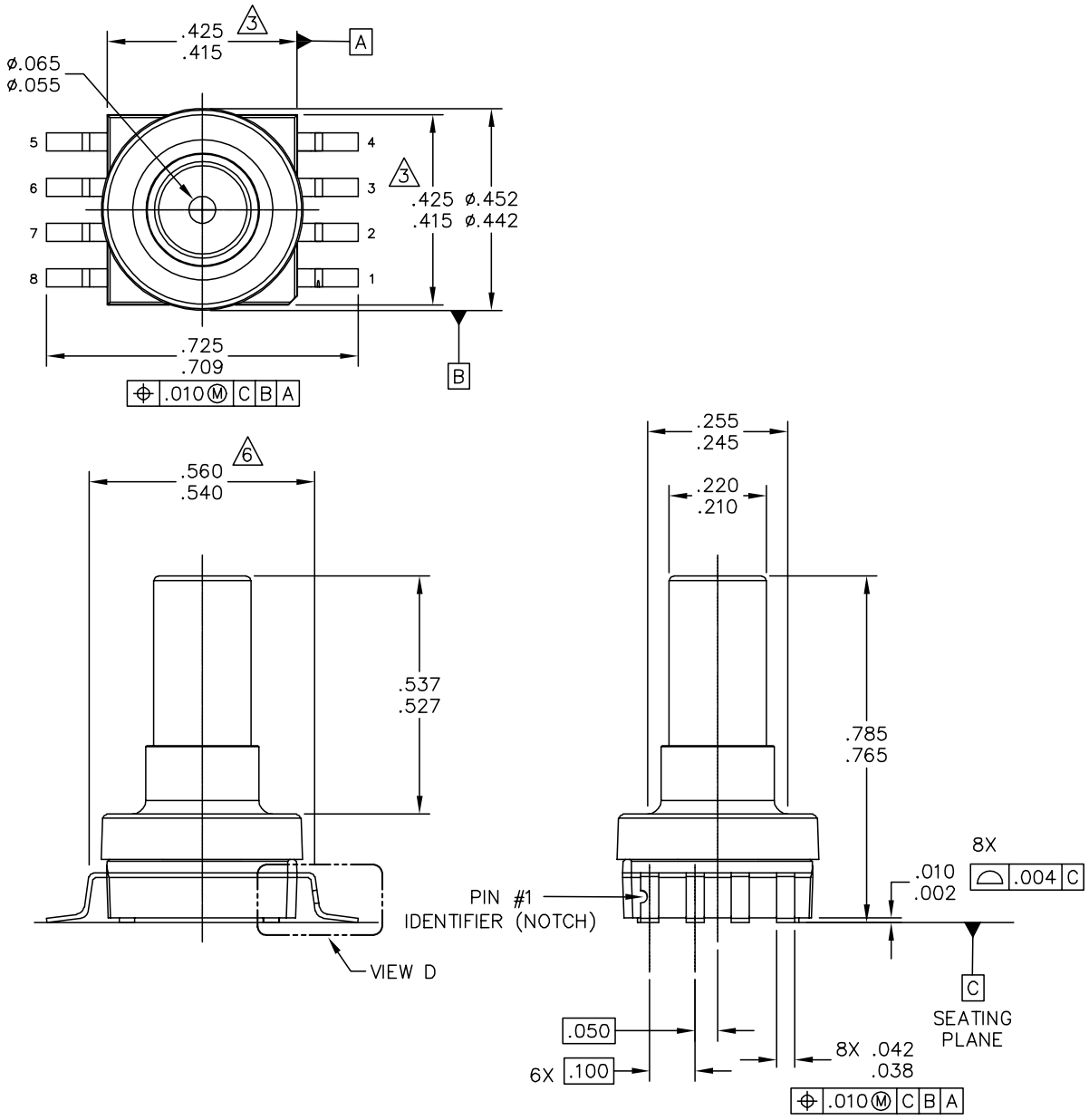


Figure 5. SOP Footprint (Case 482)

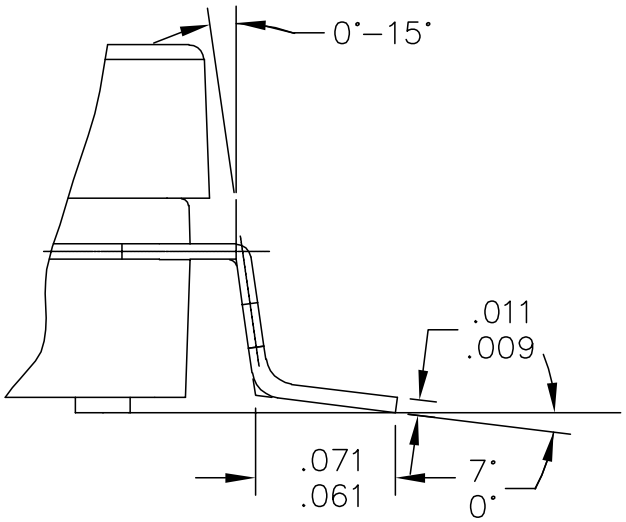
PACKAGE DIMENSIONS



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	CASE NUMBER: 1735–01	16 AUG 2005
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CASE 1735-01
ISSUE A
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VIEW D

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	CASE NUMBER: 1735–01	18 AUG 2005
	STANDARD: NON–JEDEC	

CASE 1735-01
ISSUE A
SMALL OUTLINE PACKAGE

PACKAGE DIMENSIONS

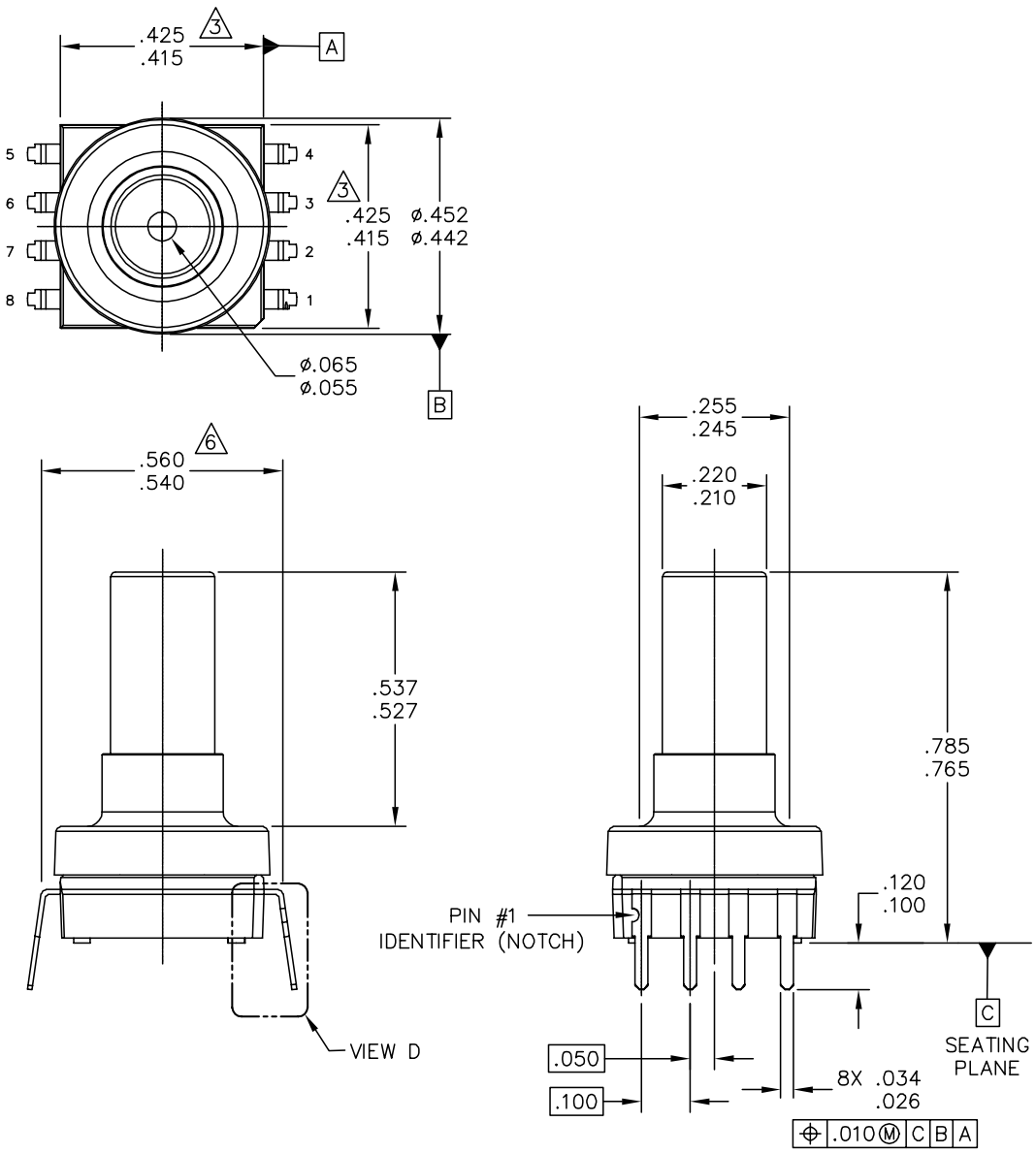
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1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M – 1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION IS .006.
5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.
6. DIMENSION TO CENTER OF LEAD WHEN FORMED PARALLEL.

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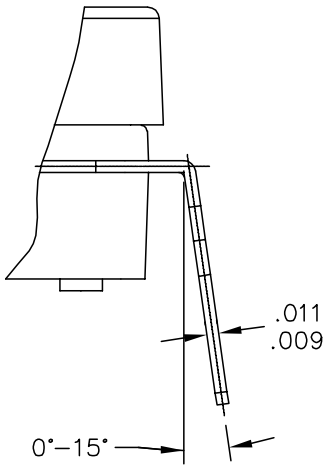
CASE 1735-01
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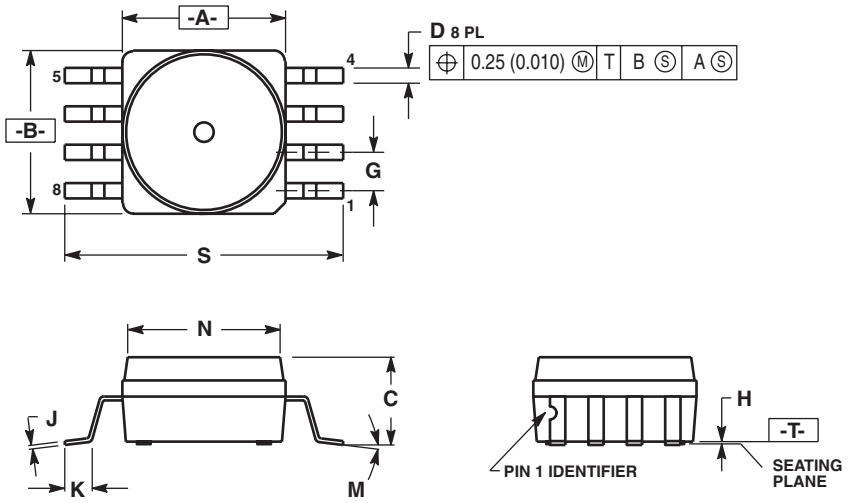
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ISSUE C
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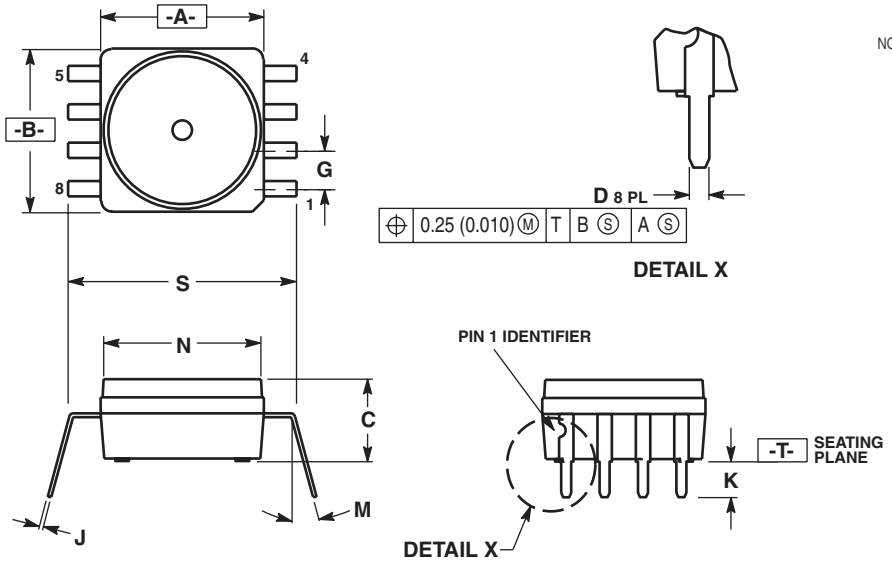
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3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.415	0.425	10.54	10.79
B	0.415	0.425	10.54	10.79
C	0.212	0.230	5.38	5.84
D	0.038	0.042	0.96	1.07
G	0.100 BSC		2.54 BSC	
H	0.002	0.010	0.05	0.25
J	0.009	0.011	0.23	0.28
K	0.061	0.071	1.55	1.80
M	0°	7°	0°	7°
N	0.405	0.415	10.29	10.54
S	0.709	0.725	18.01	18.41

CASE 482-01
ISSUE O
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6. DIMENSION S TO CENTER OF LEAD WHEN FORMED PARALLEL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.415	0.425	10.54	10.79
B	0.415	0.425	10.54	10.79
C	0.210	0.220	5.33	5.59
D	0.026	0.034	0.66	0.864
G	0.100 BSC		2.54 BSC	
J	0.009	0.011	0.23	0.28
K	0.100	0.120	2.54	3.05
M	0°	15°	0°	15°
N	0.405	0.415	10.29	10.54
S	0.540	0.560	13.72	14.22

CASE 482B-03
ISSUE B
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